

Chong Wang

List of Publications by Year in descending order

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citing authors

#	ARTICLE	IF	CITATIONS
1	PET Surface Modification with Inkjet-Printing Pd ²⁺ /Epoxy Resin Solution for Selective Electroless Copper Plating. ACS Applied Electronic Materials, 2022, 4, 149-157.	4.3	7
2	Effect of 3-mercapto-1-propane sulfonate sulfonic acid and polyvinylpyrrolidone on the growth of cobalt pillar by electrodeposition. Nanotechnology Reviews, 2022, 11, 1209-1218.	5.8	5
3	Enhancing peel strength between liquid crystal polymer and copper with plasma treatment, surface oxidation, and silane coating. Journal of Applied Polymer Science, 2022, 139, .	2.6	1
4	Embedded Magnetic Solenoid Inductor Into Organic Packaging Substrate Using Lithographic via Technology for Power Supply Module Integration. IEEE Transactions on Electron Devices, 2022, , 1-7.	3.0	1
5	Polymer-based Cu/Ag composite as seed layer on insulating substrate for copper addition of multi-dimensional conductive patterns. Journal of the Taiwan Institute of Chemical Engineers, 2021, 123, 254-260.	5.3	3
6	Label-free diagnosis for colorectal cancer through coffee ring-assisted surface-enhanced Raman spectroscopy on blood serum. Journal of Biophotonics, 2020, 13, e201960176.	2.3	52
7	Hydroquinone oriented growth control to achieve high-quality copper coating at high rate for electronics interconnection. Journal of the Taiwan Institute of Chemical Engineers, 2020, 112, 130-136.	5.3	10
8	Surface coarsening of carbon fiber/cyanate ester composite for adhesion improvement of electroless copper plating as conductive patterns. Materials Chemistry and Physics, 2020, 255, 123597.	4.0	9
9	Investigation of polyvinylpyrrolidone as an inhibitor for trench super-filling of cobalt electrodeposition. Journal of the Taiwan Institute of Chemical Engineers, 2020, 112, 232-239.	5.3	13
10	Quick development of copper electroplating formula for via and trench filling by an experiential method. , 2020, , .		1
11	Copolymer of Pyrrole and 1,4-Butanediol Diglycidyl as an Efficient Additive Leveler for Through-Hole Copper Electroplating. ACS Omega, 2020, 5, 4868-4874.	3.5	37
12	Whisker inhibited Sn-Bi alloy coating on copper surface to increase copper bonding strength for signal loss reduction of PCB in high-frequency. Applied Surface Science, 2020, 513, 145718.	6.1	12
13	Cyanide-free silver immersion deposition involving 3-mercapto-1-propanesulfonic acid for copper finishing. Materials Chemistry and Physics, 2020, 244, 122671.	4.0	9
14	Optoplasmonic Hybrid Materials for Trace Detection of Methamphetamine in Biological Fluids through SERS. ACS Applied Materials & Interfaces, 2020, 12, 24192-24200.	8.0	43
15	Communication Localized Accelerator Pre-Adsorption to Speed Up Copper Electroplating Microvia Filling. Journal of the Electrochemical Society, 2019, 166, D467-D469.	2.9	3
16	Compatible Ag ⁺ Complex-Assisted Ultrafine Copper Pattern Deposition on Poly(ethylene) Terephthalate (PET) Overlaid on BT Substrate. ACS Applied Materials & Interfaces, 2019, 11, 44811-44819.	8.0	36
17	Air-plasma surface modification of epoxy resin substrate to improve electroless copper plating of printed circuit board. Vacuum, 2019, 170, 108967.	3.5	16
18	Convection-Dependent Competitive Adsorption between SPS and EO/PO on Copper Surface for Accelerating Trench Filling. Journal of the Electrochemical Society, 2019, 166, D93-D98.	2.9	14

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19	Numerical simulation and experiments to improve throwing power for practical PCB through-holes plating. <i>Circuit World</i> , 2019, 45, 221-230.	0.9	9
20	Computational analysis and experimental evidence of two typical levelers for acid copper electroplating. <i>Electrochimica Acta</i> , 2018, 273, 318-326.	5.2	55
21	A comparison of typical additives for copper electroplating based on theoretical computation. <i>Computational Materials Science</i> , 2018, 147, 95-102.	3.0	49
22	Enhancing adhesion performance of no-flow prepreg to form multilayer structure of printed circuit boards with plasma-induced surface modification. <i>Surface and Coatings Technology</i> , 2018, 333, 24-31.	4.8	12
23	Preparation and Properties of Cyanate/Epoxy-based Composite with Thermal Conductive Silica Particles. <i>IOP Conference Series: Materials Science and Engineering</i> , 2018, 422, 012003.	0.6	0
24	Investigation of poly (1-vinyl imidazole co 1, 4-butanediol diglycidyl ether) as a leveler for copper electroplating of through-hole. <i>Electrochimica Acta</i> , 2018, 283, 560-567.	5.2	49
25	Electrochemical Factors of Levelers on Plating Uniformity of Through-Holes: Simulation and Experiments. <i>Journal of the Electrochemical Society</i> , 2018, 165, E359-E365.	2.9	14
26	Improvement of plating uniformity for copper patterns of IC substrate with multi-physics coupling simulation. <i>Circuit World</i> , 2018, 44, 150-160.	0.9	6
27	Incorporation of Tin on copper clad laminate to increase the interface adhesion for signal loss reduction of high-frequency PCB lamination. <i>Applied Surface Science</i> , 2017, 422, 738-744.	6.1	27
28	Improving wettability of photo-resistive film surface with plasma surface modification for coplanar copper pillar plating of IC substrates. <i>Applied Surface Science</i> , 2017, 411, 82-90.	6.1	13
29	Preparation of rimose NiZnP electrode for hydrogen evolution reaction in alkaline medium by electroless and H ₂ SO ₄ etching. <i>Journal of Alloys and Compounds</i> , 2017, 719, 376-382.	5.5	8
30	Investigation of benzoquinone as a new type of Cu electroplating additive. , 2017, , .		3
31	Multi-physics coupling aid uniformity improvement in pattern plating. <i>Circuit World</i> , 2016, 42, 69-76.	0.9	7
32	Initiation electroless nickel plating by atomic hydrogen for PCB final finishing. <i>Chemical Engineering Journal</i> , 2016, 306, 117-123.	12.7	15
33	Fabrication of silver electrically conductive adhesive to apply in through-hole filling for PCB interconnection. <i>Journal of Materials Science: Materials in Electronics</i> , 2016, 27, 9186-9190.	2.2	8
34	Effects of additives on filling blind vias for HDI manufacture. , 2015, , .		0
35	Multiphysics coupling simulation of RDE for PCB manufacturing. <i>Circuit World</i> , 2015, 41, 20-28.	0.9	12
36	Study on brown oxidation process with imidazole group, mercapto group and heterocyclic compounds in printed circuit board industry. <i>Journal of Adhesion Science and Technology</i> , 2015, 29, 1178-1189.	2.6	14

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37	Improved Uniformity of Conformal Through-Hole Copper Electrodeposition by Revision of Plating Cell Configuration. <i>Journal of the Electrochemical Society</i> , 2015, 162, D575-D583.	2.9	21
38	A better understanding of the capacity fading mechanisms of $\text{Li}_3\text{V}_2(\text{PO}_4)_3$. <i>RSC Advances</i> , 2015, 5, 71684-71691.	3.6	21
39	Electrochemical Investigation Cu Corrosion Behaviour of Electronic Circuit Board in Base Electrolyte. <i>Applied Mechanics and Materials</i> , 2014, 556-562, 141-144.	0.2	0
40	Preparation of electronic-grade CuO for copper electrodeposition of printed circuit boards. <i>Circuit World</i> , 2014, 40, 127-133.	0.9	0
41	Plating Uniformity of Bottom-up Copper Pillars and Patterns for IC Substrates with Additive-assisted Electrodeposition. <i>Electrochimica Acta</i> , 2014, 120, 293-301.	5.2	77
42	Electrochemical behaviors of Janus Green B in through-hole copper electroplating: An insight by experiment and density functional theory calculation using Safranin T as a comparison. <i>Electrochimica Acta</i> , 2013, 92, 356-364.	5.2	94
43	Prediction of a new leveler (N-butyl-methyl piperidinium bromide) for through-hole electroplating using molecular dynamics simulations. <i>Electrochemistry Communications</i> , 2012, 18, 104-107.	4.7	57
44	A Catalytic and Interfacing PEDOT:PSS/CuPc Polymerized on Cloth Fiber to Electro- μ Metalize Stretchable Copper Conductive Pattern. <i>Advanced Materials Interfaces</i> , 0, , 2101462.	3.7	2